## 44-volt, $5.5-\mathrm{amp}$, quad power half bridge

## Features

- Multipower BCD technology
- Minimum input, output pulse width distortion
- $150-\mathrm{m} \Omega \mathrm{R}_{\mathrm{dsON}}$ complementary DMOS output stage
- CMOS compatible logic inputs
- Thermal protection

■ Thermal-warning output

- Undervoltage protection
- Short-circuit protection


## Description

STA510A is a monolithic quad half bridge stage in Multipower BCD Technology. The device can be used as dual bridge or reconfigured, by connecting pin CONFIG to $\mathrm{V}_{\mathrm{DD}}$, as a single bridge with double current capability, or as half bridges (Binary mode) with half current capability.

The device is intended for the output stage of a stereo all-digital high-efficiency (DDX ${ }^{\circledR}$ ) amplifier which employs a pulse-width modulator driver.


The STA510A is capable of delivering an output power of 50 W into $3 \Omega \times 4$ channels with THD $=10 \%$ at $\mathrm{V}_{\mathrm{CC}}=37 \mathrm{~V}$ in single ended configuration. It can also deliver $100 \mathrm{~W}+100 \mathrm{~W}$ into $6-\Omega$ loads with $\mathrm{THD}=10 \%$ at $\mathrm{V}_{\mathrm{CC}}=36 \mathrm{~V}$ in BTL configuration and 200W into $3 \Omega$ with $\mathrm{THD}=10 \%$ at $\mathrm{V}_{\mathrm{CC}}=36 \mathrm{~V}$ in single paralleled BTL configuration.

The input pins have a threshold proportional to the voltage on pin VL.

Table 1. Device summary

| Order code | Operating temp. range | Package | Packaging |
| :--- | :--- | :--- | :--- |
| STA510A | 0 to $70^{\circ} \mathrm{C}$ | PowerSO36 EPU | Tube |
| STA510A13TR | 0 to $70^{\circ} \mathrm{C}$ | PowerSO36 EPU | Tape and reel |

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## 1 Audio applications circuit

Figure 1. Audio applications circuit (dual BTL)


## 2 Pins description

Figure 2. Pin connection (top view)


Table 2. Pin functions

| Pin | Name |  |
| :---: | :---: | :--- |
| 1 | GNDSUB | Substrate ground |
| 2,3 | OUT2B | Output half bridge 2B |
| 4 | VCC2B | Positive supply |
| 5 | GND2B | Negative supply |
| 6 | GND2A | Negative supply |
| 7 | VCC2A | Positive supply |
| 8,9 | OUT2A | Output half bridge 2A |
| 10,11 | OUT1B | Output half bridge 1B |
| 12 | VCC1B | Positive supply |
| 13 | GND1B | Negative supply |
| 14 | GND1A | Negative supply |
| 15 | VCC1A | Positive supply |
| 16,17 | OUT1A | Output half bridge 1A |

Table 2. Pin functions (continued)

| Pin | Name | Description |
| :---: | :---: | :---: |
| 18 | NC | No internal connection |
| 19 | GNDCLEAN | Logical ground |
| 20 | GNDREG | Ground for regulator $\mathrm{V}_{\mathrm{DD}}$ |
| 21, 22 | VDD | $5-\mathrm{V}$ regulator referred to ground |
| 23 | VL | Logic reference voltage |
| 24 | CONFIG | Configuration pin: <br> 0 : normal operation <br> 1: single BTL (mono) mode, join the pins OUT1A to OUT1B and OUT2A to OUT2B (if IN1A is joined to IN1B and IN2A to IN2B) |
| 25 | PWRDN | Standby (power down): <br> 0: low power consumption mode <br> 1: normal operation |
| 26 | TRISTATE | High impedance control: <br> 0 : all power amplifiers in high-impedance state <br> 1: normal operation |
| 27 | FAULT ${ }^{(1)}$ | Fault advisor: <br> 0 : fault detected (short circuit or thermal) <br> 1: normal operation |
| 28 | THWARN ${ }^{(1)}$ | Thermal warning advisor: <br> 0: junction temperature $=130^{\circ} \mathrm{C}$ <br> 1: normal operation |
| 29 | IN1A | Input of half bridge 1A |
| 30 | IN1B | Input of half bridge 1B |
| 31 | IN2A | Input of half bridge 2A |
| 32 | IN2B | Input of half bridge 2B |
| 33, 34 | VSS | $5-\mathrm{V}$ regulator referred to $+\mathrm{V}_{\mathrm{CC}}$ |
| 35, 36 | VCCSIG | Signal positive supply |
| - | EP | Exposed pad up |

1. The pin is open collector. To have a high logic value it needs to be pulled up by a resistor.

## 3 Electrical specifications

### 3.1 Absolute maximum ratings

Table 3. Absolute maximum ratings

| Symbol | Parameter | Min | Typ | Max | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- |
| $\mathrm{V}_{\mathrm{CC}}$ | DC supply voltage (pins 4,7,12,15) | - | - | 44 | V |
| $\mathrm{~V}_{\text {max }}$ | Maximum voltage on pins 23 to 32 | - | - | 5.5 | V |
| $\mathrm{~T}_{\text {op }}$ | Operating temperature range | - | - | 90 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{P}_{\text {tot }}$ | Power dissipation $\left(\mathrm{T}_{\text {case }}=70^{\circ} \mathrm{C}\right.$ ) | - | - | 21 | W |
| $\mathrm{~T}_{\text {stg }}$ | Storage temperature | -40 | - | 150 | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\mathrm{j}}$ | Junction operating temperature | -40 | - | 150 | ${ }^{\circ} \mathrm{C}$ |

### 3.2 Recommended operating conditions

Table 4. Recommended operating conditions (*)

| Symbol | Parameter | Min | Typ | Max | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- |
| $\mathrm{V}_{\mathrm{CC}}$ | DC supply voltage | 10 | - | 39.0 | V |
| $\mathrm{~V}_{\mathrm{L}}$ | Input logic reference | 2.7 | 3.3 | 5.0 | V |
| $\mathrm{~T}_{\mathrm{amb}}$ | Ambient temperature | 0 | - | 70 | ${ }^{\circ} \mathrm{C}$ |

$\left(^{*}\right)$ performances not guaranteed beyond recommended operating conditions

### 3.3 Thermal data

Table 5. Thermal data

| Symbol | Parameter | Min | $\mathbf{T y p}$ | Max | Unit |
| :--- | :--- | :--- | :--- | :--- | :--- |
| $\mathrm{T}_{\mathrm{j} \text {-case }}$ | Thermal resistance junction to case (thermal pad) | - | 1 | 2.5 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\mathrm{T}_{\text {jSD }}$ | Thermal shut-down junction temperature | - | 150 | - | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{T}_{\text {warn }}$ | Thermal warning temperature | - | 130 | - | ${ }^{\circ} \mathrm{C}$ |
| $\mathrm{t}_{\text {hSD }}$ | Thermal shut-down hysteresis | - | 25 | - | ${ }^{\circ} \mathrm{C}$ |

The power dissipated within the device depends primarily on the supply voltage, load impedance and output modulation level. The PowerSO36 package of the STA510A includes an exposed pad or slug on the top of the device to provide a direct thermal path from the die to the heatsink.

### 3.4 Electrical characteristics

The specifications given here were obtained with the conditions $\mathrm{V}_{\mathrm{L}}=3.3 \mathrm{~V}, \mathrm{~V}_{\mathrm{CC}}=36 \mathrm{~V}$, $R_{L}=8 \Omega, f_{s w}=384 \mathrm{kHz}$ and $\mathrm{T}_{\mathrm{amb}}=25^{\circ} \mathrm{C}$ unless otherwise specified. See also Figure 3.

Table 6. Electrical characteristics

| Symbol | Parameter | Test conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| $\mathrm{R}_{\text {dsON }}$ | Power P-channel / N-channel MOSFET RdsON | $\mathrm{I}_{\mathrm{d}}=1 \mathrm{~A}$ | - | 150 | 200 | $\mathrm{m} \Omega$ |
| $\mathrm{I}_{\text {dss }}$ | Power P-channel / N-channel leakage | - | - | - | 100 | $\mu \mathrm{A}$ |
| $\mathrm{g}_{\mathrm{N}}$ | Power P-channel RdsON matching | $\mathrm{I}_{\mathrm{d}}=1 \mathrm{~A}$ | 95 | - | - | \% |
| $\mathrm{gr}_{\mathrm{P}}$ | Power N-channel RdsON matching | $\mathrm{I}_{\mathrm{d}}=1 \mathrm{~A}$ | 95 | - | - | \% |
| Dt_s | Low current dead time (static) | See test circuit in Figure 3 | - | 10 | 20 | ns |
| Dt_d | High current dead time (dynamic) | $\begin{aligned} & \mathrm{L}=22 \mu \mathrm{H}, \\ & \mathrm{C}=470 \mathrm{nF}, \\ & \mathrm{R}_{\mathrm{L}}=8 \Omega, \\ & \mathrm{I}_{\mathrm{d}}=3 \mathrm{~A}, \\ & \text { seeFigure } 5 \end{aligned}$ | - | - | 50 | ns |
| $\mathrm{t}_{\mathrm{d}} \mathrm{ON}$ | Turn-on delay time | Resistive load, $V_{C C}=30 \mathrm{~V}$ | - | - | 100 | ns |
| $\mathrm{t}_{\text {d OFF }}$ | Turn-off delay time | Resistive load, $\mathrm{V}_{\mathrm{CC}}=30 \mathrm{~V}$ | - | - | 100 | ns |
| $\mathrm{t}_{\mathrm{r}}$ | Rise time | Resistive load, see Figure 3 | - | - | 25 | ns |
| $\mathrm{t}_{\mathrm{f}}$ | Fall time |  | - | - | 25 | ns |
| $\mathrm{V}_{\text {INH }}$ | High-level input voltage | - | - | - | $\begin{aligned} & \mathrm{V}_{\mathrm{L}} / 2+ \\ & 300 \mathrm{mV} \end{aligned}$ | V |
| $\mathrm{V}_{\text {INL }}$ | Low-level input voltage | - | $\begin{aligned} & \mathrm{V}_{\mathrm{L}} / 2- \\ & 300 \mathrm{mV} \end{aligned}$ | - | - | V |
| $\mathrm{I}_{\mathrm{INH}}$ | High-level Input current | Pin voltage $=\mathrm{V}_{\mathrm{L}}$ | - | 1 | - | $\mu \mathrm{A}$ |
| $\mathrm{I}_{\text {INL }}$ | Low-level input current | Pin voltage $=0.3 \mathrm{~V}$ | - | 1 | - | $\mu \mathrm{A}$ |
| IPWRDNH | High-level PWRDN pin input current | $\mathrm{V}_{\mathrm{L}}=3.3 \mathrm{~V}$ | - | 35 | - | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\text {LOW }}$ | Low logical-state voltage (pins PWRDN, TRISTATE) | $\mathrm{V}_{\mathrm{L}}=2.7 \mathrm{~V}$ | - | - | 0.70 | V |
|  |  | $\mathrm{V}_{\mathrm{L}}=3.3 \mathrm{~V}$ | - | - | 0.80 | V |
|  |  | $\mathrm{V}_{\mathrm{L}}=5.0 \mathrm{~V}$ | - | - | 0.85 | V |
| $\mathrm{V}_{\text {HIGH }}$ | High logical-state voltage (pins PWRDN, TRISTATE) | $\mathrm{V}_{\mathrm{L}}=2.7 \mathrm{~V}$ | 1.50 | - | - | V |
|  |  | $\mathrm{V}_{\mathrm{L}}=3.3 \mathrm{~V}$ | 1.70 | - | - | V |
|  |  | $\mathrm{V}_{\mathrm{L}}=5.0 \mathrm{~V}$ | 1.85 | - | - | V |
| ICCPWRDN | Supply current from $\mathrm{V}_{\mathrm{CC}}$ in power down | $\mathrm{V}_{\text {PWRDN }}=0 \mathrm{~V}$ | - | - | 3 | mA |
| $\mathrm{I}_{\text {FAULT }}$ | Output current on pins FAULT and THWARN with fault conditions | $\mathrm{V}_{\text {pin }}=3.3 \mathrm{~V}$ | - | 1 | - | mA |

Table 6. Electrical characteristics (continued)

| Symbol | Parameter | Test conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| IVCCHIz | Supply current from $\mathrm{V}_{\mathrm{CC}}$ in 3-state | $\begin{aligned} & \mathrm{V}_{\mathrm{CC}}=30 \mathrm{~V}, \\ & \mathrm{~V}_{\text {TRISTATE }}=0 \mathrm{~V} \end{aligned}$ | - | 22 | - | mA |
| $\mathrm{I}_{\mathrm{Vcc}}$ | Supply current from $\mathrm{V}_{\mathrm{CC}}$ in operation (both channels switching) | $\mathrm{V}_{\mathrm{CC}}=30 \mathrm{~V},$ <br> Input pulse width = 50\% duty, <br> switching frequency $=384 \mathrm{kHz},$ <br> no LC filters | - | 70 | - | mA |
| ISCP | Short-circuit current limit | - | 5.5 | 6 | - | A |
| $\mathrm{V}_{\text {UVP }}$ | Undervoltage protection threshold | - | - | 7 | - | V |
| $\mathrm{t}_{\text {pw_min }}$ | Output minimum pulse width | No load | 25 | - | 40 | ns |
| ESD | ESD maximum withstanding voltage range, test condition CDF-AEC-Q100-002- "Human Body Model" |  | +/-1500V |  |  | V |

Table 7. Logic truth table

| TRISTATE | INxA | INxB | Q1 |  | Q2 | Q3 | Qutput <br> mode |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- | :--- |
| 0 | X | X | Off | Off | Off | Off | Hi-Z |
| 1 | 0 | 0 | Off | Off | On | On | Dump |
| 1 | 0 | 1 | Off | On | On | Off | Negative |
| 1 | 1 | 0 | On | Off | Off | On | Positive |
| 1 | 1 | 1 | On | On | Off | Off | Not used |

Figure 3. Test circuit for low current dead time for single-ended applications


Figure 4. Block diagram for high current dead time for bridge applications


Figure 5. Test circuit for high current dead time for bridge applications


## 4 Technical information

The STA510A is a dual channel H-bridge that is able to deliver 100 W per channel (into $R_{L}=6 \Omega$ with $\mathrm{THD}=10 \%$ and $\mathrm{V}_{\mathrm{CC}}=36 \mathrm{~V}$ ) of audio output power very efficiently. It operates in conjunction with a pulse-width modulator driver such as the STA321 or STA309A.

The STA510A converts ternary-, phase-shift- or binary-controlled PWM signals into audio power at the load. It includes a logic interface, integrated bridge drivers, high efficiency MOSFET outputs and thermal and short-circuit protection circuitry.
In differential mode (ternary, phase-shift or binary differential), two logic level signals per channel are used to control high-speed MOSFET switches to connect the speaker load to the input supply or to ground in a bridge configuration, according to the damped ternary modulation operation.
In binary mode, both full bridge and half bridge modes are supported. The STA510A includes overcurrent and thermal protection as well as an undervoltage lockout with automatic recovery. A thermal warning status is also provided.

Figure 6. Block diagram of full-bridge DDX ${ }^{\circledR}$ or binary mode


Figure 7. Block diagram of binary half-bridge mode


### 4.1 Logic interface and decode

The STA510A power outputs are controlled using one or two logic-level timing signals. In order to provide a proper logic interface, the VL input must operate at the same voltage as the DDX control logic supply.

### 4.2 Protection circuitry

The STA510A includes protection circuitry for overcurrent and thermal overload conditions. A thermal warning pin (THWARN, pin 28, open drain MOSFET) is activated low when the IC temperature exceeds $130^{\circ} \mathrm{C}$, just in advance of thermal shutdown. When a fault condition is detected an internal fault signal immediately disables the output power MOSFETs, placing both H-bridges in a high-impedance state. At the same time the open-drain MOSFET of pin FAULT (pin 27) is switched on.

There are two possible modes subsequent to activating a fault.

- Shutdown mode: with pins FAULT (with pull-up resistor) and TRISTATE separate, an activated fault disables the device, signalling a low at pin FAULT output.
The device may subsequently be reset to normal operation by toggling pin TRISTATE from high to low to high using an external logic signal.
- Automatic recovery mode: This is shown in the applications circuits below where pins FAULT and TRISTATE are connected together to a time-constant circuit (R59 and C58). An activated fault forces a reset on pin TRISTATE causing normal operation to resume following a delay determined by the time constant of the circuit. If the fault condition persists, the circuit operation repeats until the fault condition is cleared.
An increase in the time constant of the circuit produces a longer recovery interval. Care must be taken in the overall system design not to exceed the protection thesholds under normal operation.


### 4.3 Power outputs

The STA510A power and output pins are duplicated to provide a low-impedance path for the device bridged outputs. All duplicate power, ground and output pins must be connected for proper operation.
The PWRDN or TRISTATE pin should be used to set all power MOSFETs to the high-impedance state during power-up until the logic power supply, $\mathrm{V}_{\mathrm{L}}$, has settled.

### 4.4 Parallel output / high current operation

When using the DDX mode output, the STA510A outputs can be connected in parallel in order to increase the output current capability to a load. In this configuration the STA510A can provide up to 200 W into a $3-\Omega$ load.
This mode of operation is enabled with the pin CONFIG (pin 24) connected to pin VDD. The inputs are joined so that IN1A $=\operatorname{IN} 1 B, I N 2 A=I N 2 B$ and similarly the outputs
OUT1A = OUT1B, OUT2A = OUT2B as shown in Figure 9 on page 12

### 4.5 Output filtering

A passive 2nd-order filter is used on the STA510A power outputs to reconstruct the analog audio signal. System performance can be significantly affected by the output filter design and choice of passive components. A filter design for 6 - or $8-\Omega$ loads is shown in the application circuit of Figure 8, and for $4-\Omega$ loads in Figure 9 and Figure 10.

### 4.6 Applications circuits

Figure 8. Typical stereo full bridge configuration for up to $2 x 100 \mathrm{~W}$


Figure 9. Typical single BTL configuration for up to 180 W


Figure 10. Typical quad half bridge configuration for up to $4 \times 50 \mathrm{~W}$


Note: 1 In the above three circuits a PWM modulator as driver is needed.
2 The power estimations were made using the STA321+STA510A demo board. The peak power duration is for $t \leq 1 \mathrm{~s}$.

## 5 Package mechanical data

Figure 11. PowerSO36 EPU outline drawing package dimension



Table 8. PowerSO36 EPU package dimension

| Symbol | mm |  |  | inch |  |  |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- |
|  | Min | Typ |  | Max | Min |  |
| A | 3.25 | - | 3.43 | 0.128 | - | Max |
| A2 | 3.10 | - | 3.20 | 0.122 | - | 0.135 |
| A4 | 0.80 | - | 1.00 | 0.031 | - | 0.126 |
| A5 | - | 0.20 | - | - | 0.008 | - |
| a1 | 0.03 | - | -0.04 | 0.001 | - | -0.002 |
| b | 0.22 | - | 0.38 | 0.009 | - | 0.015 |
| c | 0.23 | - | 0.32 | 0.009 | - | 0.013 |
| D | 15.80 | - | 16.00 | 0.622 | - | 0.630 |
| D1 | 9.40 | - | 9.80 | 0.370 | - | 0.386 |
| D2 | - | 1.00 | - | - | 0.039 | - |
| E | 13.90 | - | 14.50 | 0.547 | - | 0.571 |
| E1 | 10.90 | - | 11.10 | 0.429 | - | 0.437 |
| E2 | - | - | 2.90 | - | - | 0.114 |
| E3 | 5.80 | - | 6.20 | 0.228 | - | 0.244 |
| E4 | 2.90 | - | 3.20 | 0.114 | - | 0.126 |
| e | - | 0.65 | - | - | 0.026 | - |
| e3 | - | 11.05 | - | - | 0.435 | - |
| G | 0 | - | 0.08 | 0 | - | 0.003 |
| H | 15.50 | - | 15.90 | 0.610 | - | 0.626 |
| h | - | - | 1.10 | - | - | 0.043 |
| L | 0.80 | - | 1.10 | 0.031 | - | 0.043 |
| M | 2.25 | - | 2.60 | 0.089 | - | 0.102 |
| N | - | - | 10 degrees | - | - | 10 degrees |
| R | - | 0.6 | - | - | 0.024 | - |
| s | - | - | 8 degrees | - | - | 8 degrees |

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## 6 Revision history

Table 9. Document revision history

| Date | Revision | Changes |
| :---: | :---: | :--- |
| October 2004 | 1 | Initial release. |
| 11-Mar-2010 | 2 | Updated description and applications circuits |

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